# TDF1510M-HAF

### Surface Mount Fast Recovery Bridge Rectifier Reverse Voltage - 1000 V Forward Current - 1.5 A

#### **Features**

- · Glass Passivated Chip Junction
- · High Surge Current Capability
- Halogen and Antimony Free(HAF), RoHS compliant

# 4 ABF Package

DESCRIPTION
Input Pin ( ~ )
Input Pin ( ~ )

Output Anode (+)

Output Cathode ( - )

PINNING

2

3

#### **Mechanical Data**

· Package: ABF

• Terminals: Solderable per MIL-STD-750, Method 2026

#### **Maximum Ratings and Electrical characteristics**

Single-phase, half-wave, 60 Hz, resistive or inductive load rating at 25°C, unless otherwise specified, for capacitive load, derate current by 20 %.

Decements	Symbols	Value	Units	
Parameter	Marking	.TDF1510M	-	
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	1000	V	
Maximum RMS voltage	V <sub>RMS</sub>	700	V	
Maximum DC Blocking Voltage	V <sub>DC</sub>	1000	V	
Average Forward Current T <sub>a</sub> = 5	0°C I <sub>F(AV)</sub>	1.5	Α	
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load(JEDEC Me	ethod)	50	А	
Peak Forward Surge Current 1 ms Single Half-square Superimposed on Rated Load	e-wave I <sub>FSM</sub>	90	А	
Maximum Instantaneous Forward Voltage at 1.5 A	V <sub>F</sub>	1.3	V	
Maximum DC Reverse Current at $T_a = 25$ Rated DC Blocking Voltage $T_a = 12$		0.5 100	μΑ	
Typical Junction Capacitance 1)	C <sub>j</sub>	25	pF	
Typical Thermal Resistance 2)	R <sub>eJA</sub>	70	°C/W	
Maximum Reverse Recovery Time 3)	t <sub>rr</sub>	160	ns	
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	- 55 to + 150	°C	

<sup>1)</sup> Measured at 1 MHz and applied reverse voltage of 4 V D.C.



 $<sup>^{2)}</sup>$  Mounted on glass epoxy PC board with 4 X ( 5 X 5 mm $^{2}$  ) copper pad.

 $<sup>^{3)} \, \</sup>text{Measured with I}_{\text{F}} = 0.5 \, \text{A}, \, \text{I}_{\text{R}} = 1 \, \text{A}, \, \text{I}_{\text{rr}} = 0.25 \, \text{A}.$ 

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Fig.1 Average Rectified Output Current Derating Curve

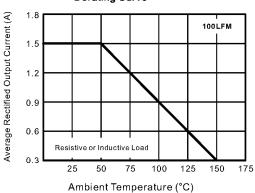


Fig.2 Typical Reverse Characteristics

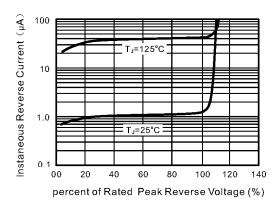


Fig.3 Typical Instaneous Forward Characteristics

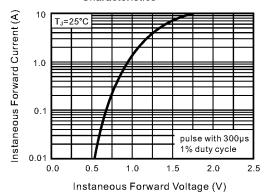


Fig.4 Typical Junction Capacitance

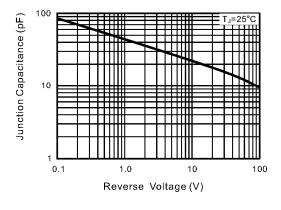
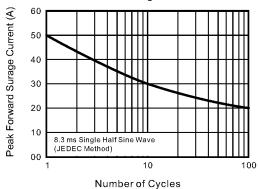


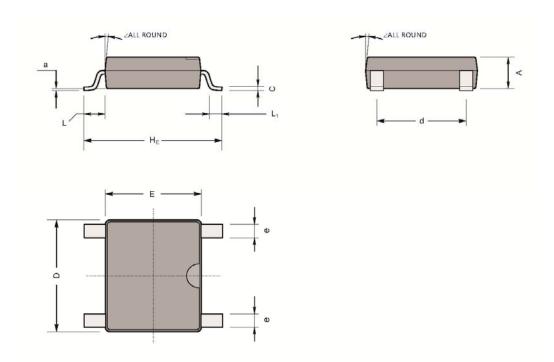
Fig.5 Maximum Non-Repetitive Peak Forward Surage Current





PACKAGE OUTLINE ABF

## Plastic surface mounted package; 4 leads



UNIT	Α	С	D	Е	H <sub>E</sub>	d	е	L	L1	а	
mm	1.2	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.1	<b>7</b> °
	1	0.15	4.9	4.2	6	3.6	0.5				

# **Recommended Soldering Footprint**

